

Bill of Materials

TI DESIGNS

Part #: TI CC3000 BoosterPack Evaluation Board

Literature #: TIDR162

DESIGNATOR	QUANTITY	DESCRIPTION	MANUFACTURER	PART NUMBER	ALTERNATIVE MANUFACTURER	ALTERNATIVE PART NUMBER
U1	1	TI CC3000 WiFi b/g Module (BM)	JORJIN	WG1300-00		WG1300-00
U2	1	IC LDO , Vout 1.2~5.5V , 1A	TI	P06.05H002.11		TPS73701DRB
J15	1	CON Male 1x2 / Pitch 2.0mm	Cherng Weei Technology Corp.	09.220024.14		P301-SGP-040/028-02
J2, J13	2	CON Male 1x3 / Pitch 2.0mm	Cherng Weei Technology Corp.	09.220034.14		P301-SGP-040/028-03
J9, J10	2	Female HEADER,2.54mm, 1X10, DIP 母座	Cherng Weei Technology Corp.	P09.380103.14		F101-SGP-D030-10
J1	1	Mini RF Header Receptacle	Hirose	11.101001.I2		U.FL-R-SMT-1(10)
J14	1	DC POWER JACK / 3Pos / Pin Diameter:0.7mm	Cherng Weei Technology Corp.	P09.014003.14		SCD471FCS000B00G
LED1	1	LED 0603, Red(Orange)	APEX	03.031111.87		RY-SP192USD84-5M
ANT1	1	ANT / 2.4GHZ / Peak Gain 0.5dB	ACX	23.101150.0F		AT8010-E2R9HAA
L2	1	IND 0402 / 1.8nH / ±0.3nH / 300mA	ACX	08.011E80.2F		HI1005-1C1N8SMT
C1	1	CAP 0402 / 1.5pF / 50V / NPO / ±0.25pF	Walsin	02.F21E50.7B		0402N1R5C500LT
C2	1	CAP 0402 / 10pF / 50V / NPO / ±5%	Walsin	02.F20100.2B		0402N100J500LT
C10	1	CAP 0402 / 0.1uF / 10V / X7R / ±10%	Walsin	02.220104.3B		0402B104K100CT
C11, C8	2	CAP 0402 / 1uF / 6.3V / Y5V / +80%~-20%	Walsin	02.320105.6B		0402F105Z6R3CT
C9	1	CAP 0603 / 10uF / 6.3V / X5R / ±10%	Walsin	02.630106.3B		0603X106K6R3CT
R5, R13, R15, R16, R17, R18, R19	7	RES 0402 / 0R / Jumper	Walsin	12.020000.2B		WR04X000PTL
R21	1	RES 0402 / 470R / 50V / ±5%	Walsin	12.020471.2B		WR04X471JTL
R23	1	RES 0402 / 30K / ±5%	YAGEO	12.020303.2D		RC0402JR-0730KL
R22	1	RES 0402 / 62K / ±5%	Walsin	12.020623.2B		WR04X623 JTL
R1, R2, R20	3	RES 0603 / 0R / Jumper	Walsin	12.030000.2B		WR06X000PTL
J2, J13, J15	3	DC JUMPER / 2.0MM PITCH	Cherng Weei Technology Corp.	09.080023.14		CMJ-20BB
	1	PCB WG1300E0B D01 / Layer 2 / FR4 (4pcs/1PNL)	Yaoxin Electronics Corp.	P01.021101.B7		WG1300E0B-PCB-D01

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